

**Surface Mount Superfast Recovery Rectifier**
**Reverse Voltage – 50 to 600 V**
**Forward Current – 3 A**
**FEATURES**

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Superfast reverse recovery time
- Lead free in comply with EU RoHS 2011/65/EU directives

**MECHANICAL DATA**

- Case: SMA
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 0.055g / 0.002oz

**PINNING**

PIN	DESCRIPTION
1	Cathode
2	Anode


 Top View  
 Marking Code:ES3A~ES3J  
 Simplified outline SMA and symbol

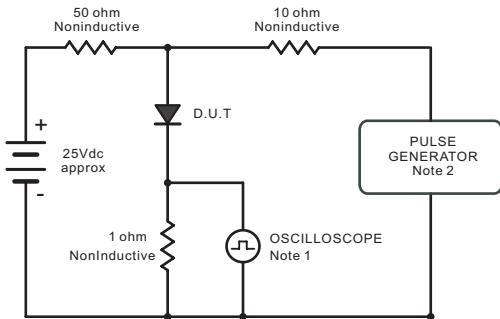
**Absolute Maximum Ratings and Characteristics**

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load.  
 For capacitive load, derate current by 20%.

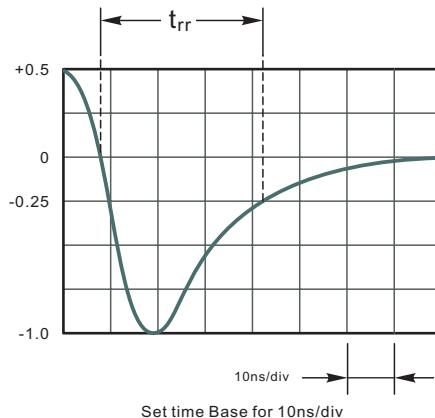
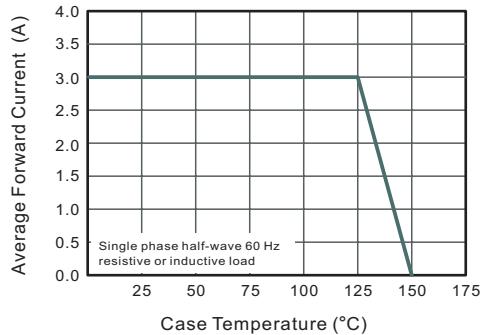
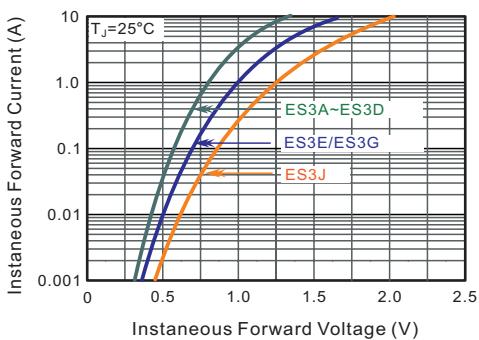
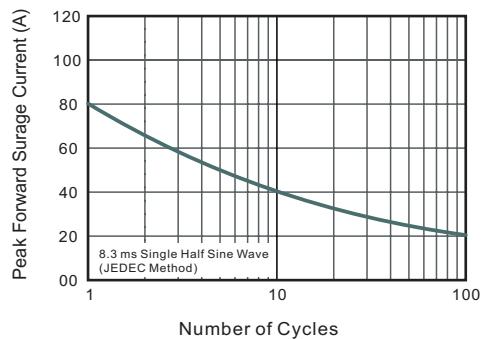
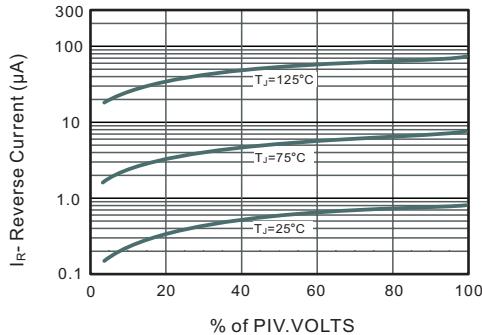
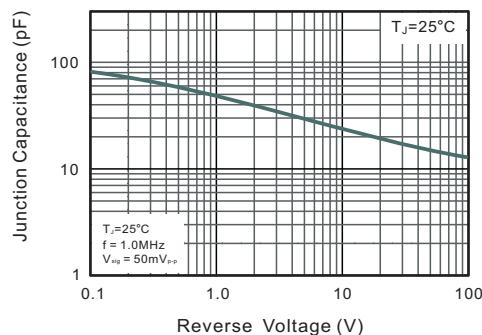
Parameter	Symbols	ES3A	ES3B	ES3C	ES3D	ES3E	ES3G	ES3J	Units
Maximum Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	50	100	150	200	300	400	600	V
Maximum RMS voltage	V <sub>RMS</sub>	35	70	105	140	210	280	420	V
Maximum DC Blocking Voltage	V <sub>DC</sub>	50	100	150	200	300	400	600	V
Maximum Average Forward Rectified Current at T <sub>c</sub> = 125 °C	I <sub>F(AV)</sub>					3			A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I <sub>FSM</sub>					80			A
Maximum Forward Voltage at 3 A	V <sub>F</sub>			1			1.25	1.68	V
Maximum DC Reverse Current T <sub>a</sub> = 25 °C at Rated DC Blocking Voltage T <sub>a</sub> = 125 °C	I <sub>R</sub>				5	100			µA
Typical Junction Capacitance at V <sub>R</sub> =4V, f=1MHz	C <sub>j</sub>				40				pF
Maximum Reverse Recovery Time <sup>(1)</sup>	t <sub>rr</sub>				35				ns
Typical Thermal Resistance <sup>(2)</sup>	R <sub>θJA</sub> R <sub>θJC</sub>				50	16			°C/W
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>stg</sub>				-55 ~ +150				°C

 ( 1 ) Measured with I<sub>F</sub> = 0.5 A, I<sub>R</sub> = 1 A, I<sub>rr</sub> = 0.25 A.

( 2 ) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

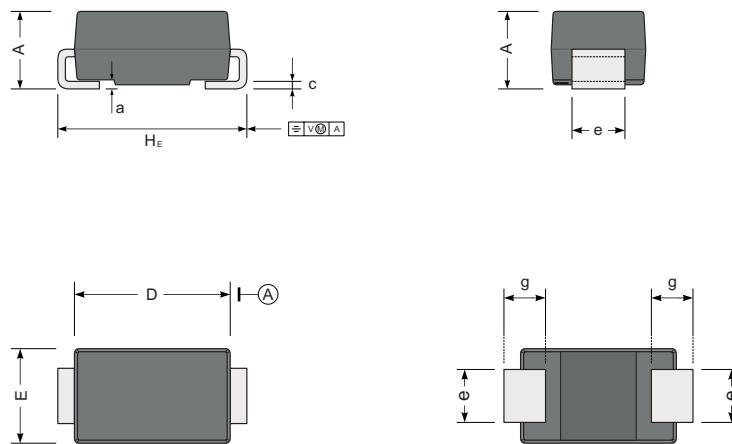
**Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram**


Note: 1. Rise Time = 7ns, max.  
 Input Impedance = 1megohm,22pF.  
 2. Ries Time =10ns, max.  
 Source Impedance = 50 ohms.

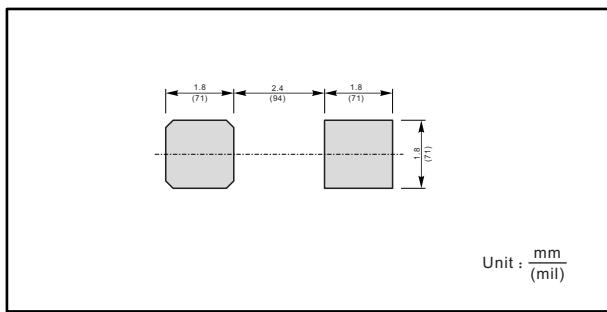

**Fig.2 Maximum Average Forward Current Rating**

**Fig.4 Typical Forward Characteristics**

**Fig.6 Maximum Non-Repetitive Peak Forward Surge Current**

**Fig.3 Typical Reverse Characteristics**

**Fig.5 Typical Junction Capacitance**


**PACKAGE OUTLINE**

Plastic surface mounted package; 2 leads

**SMA**


UNIT		A	D	E	H <sub>E</sub>	c	e	g	a
mm	max	2.2	4.5	2.7	5.2	0.31	1.6	1.5	0.3
	min	1.9	4.0	2.3	4.7	0.15	1.3	0.9	
mil	max	87	181	106	205	12	63	59	12
	min	75	157	91	185	6	51	35	

**The recommended mounting pad size**

**Marking**

Type number	Marking code
ES3A	ES3A
ES3B	ES3B
ES3C	ES3C
ES3D	ES3D
ES3E	ES3E
ES3G	ES3G
ES3J	ES3J